AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1-29. (Canceled).

30. (Currently Amended) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;

an opening in said substrate defined by said substrate material, wherein ~~said~~ borders of said substrate material form a first rectangular portion originating with an intersection of said upper surface and said opening, and a second rectangular portion, wherein said ~~second~~ first rectangular portion has larger dimensions in a horizontal direction than said ~~first~~ second rectangular portion, wherein said horizontal direction is between sidewalls of said first rectangular portion and said second rectangular portion, and wherein said sidewalls are perpendicular to said upper surface; and

a conductor filling said opening.

31. (Previously Presented) The integrated circuit in claim 30, wherein said second rectangular portion is deeper in said opening than said first rectangular portion.

32. (Previously Presented) The integrated circuit in claim 30, wherein said first rectangular portion is deeper in said opening than said second rectangular portion.

33. (Previously Presented) The integrated circuit in claim 30, wherein said second rectangular portion increases a surface area of said opening.

34. (Previously Presented) The integrated circuit in claim 30, wherein said second rectangular portion increases a capacitance of said structure.

35. (Currently Amended) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;

an opening in said substrate defined by borders of said substrate material, wherein said borders of said substrate material form a first rectangular portion originating with an intersection of said upper surface and said opening, a second rectangular portion, and a third rectangular portion, wherein said ~~second~~ first rectangular portion has larger dimensions in a horizontal direction than said ~~first~~ second rectangular portion and said third rectangular portion, wherein said horizontal direction is between sidewalls of said first, second and third rectangular ~~portion~~ portions, ~~and said second rectangular portion,~~ and wherein said sidewalls are perpendicular to said upper surface; and

a conductor filling said opening.

36. (Previously Presented) The integrated circuit in claim 35, wherein said second rectangular portion is between said first rectangular portion and said third rectangular portion.

37. (Previously Presented) The integrated circuit in claim 35, wherein said first rectangular portion and said third rectangular portion have substantially similar dimensions.

38. (Previously Presented) The integrated circuit in claim 35, wherein said second rectangular portion increases a surface area of said structure.

39. (Previously Presented) The integrated circuit in claim 35, wherein said first rectangular portion and said third rectangular portion have different dimensions in said horizontal direction.

40. (Previously Presented) An integrated circuit structure comprising:

a substrate having an upper surface, wherein said substrate comprises a substrate material;

a bottle-shaped opening in said substrate defined by borders of said substrate material, wherein said borders of said substrate material form a first rectangular portion located completely below and having no portion thereof coincident with said upper surface, and a second rectangular portion located below said first rectangular portion and bounded on two sides by a mask material deposited on said substrate material, wherein said ~~second~~ first rectangular portion has larger dimensions in a horizontal direction than said ~~first~~ second rectangular portion, wherein said horizontal direction is between sidewalls of said first rectangular portion and said second rectangular portion, and wherein said sidewalls are perpendicular to said upper surface; and

a conductor filling said opening.

41. (Previously Presented) The integrated circuit in claim 40, wherein said second rectangular portion is deeper in said opening than said first rectangular portion.

42. (Previously Presented) The integrated circuit in claim 40, wherein said first rectangular portion is deeper in said opening than said second rectangular portion.

43. (Previously Presented) The integrated circuit in claim 40, wherein said second rectangular portion increases a surface area of said bottle-shaped opening.

44. (Previously Presented) The integrated circuit in claim 40, wherein said second rectangular portion increases a capacitance of said structure.